

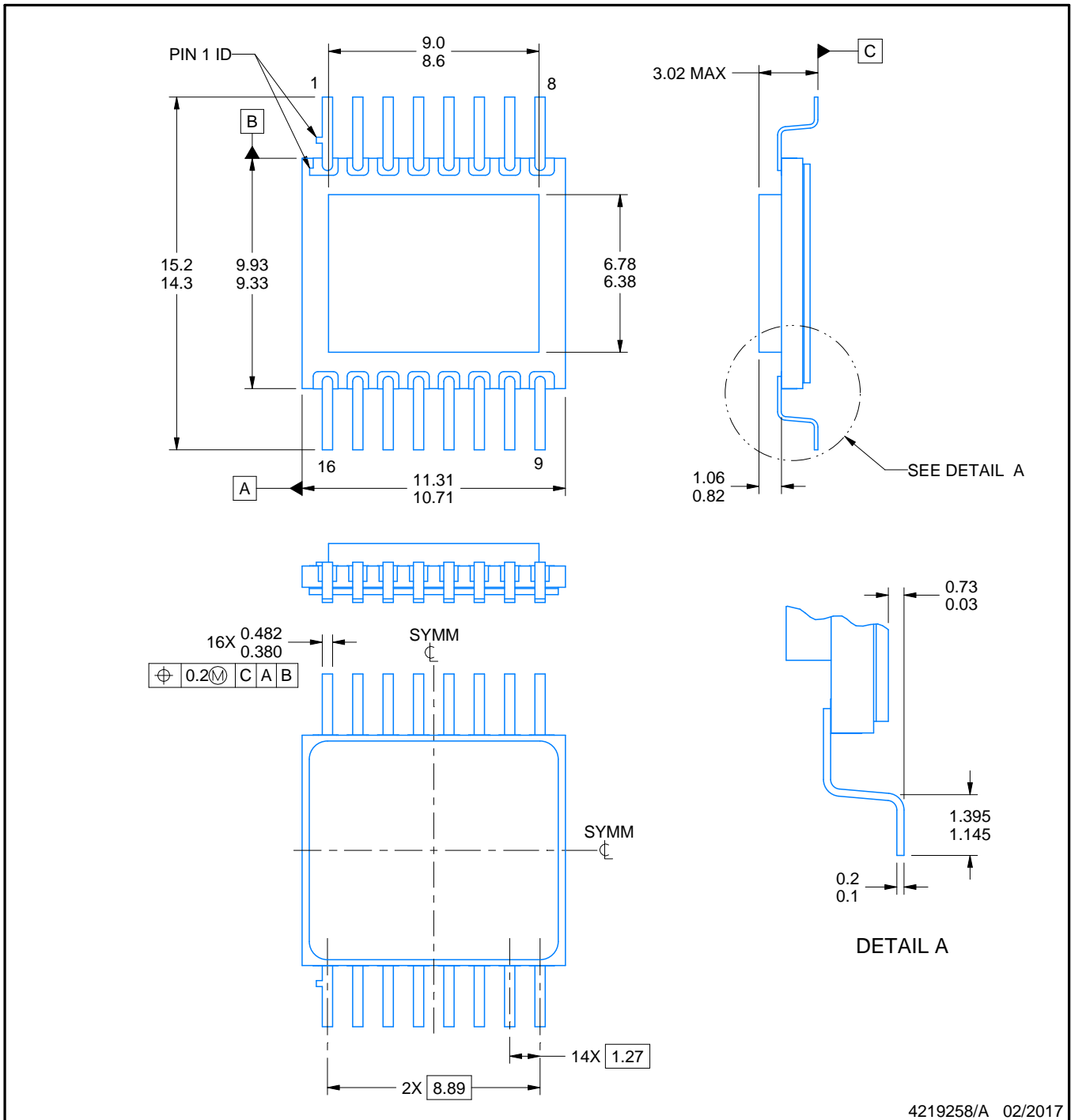
HKS0016A



PACKAGE OUTLINE

CFP - 3.02 mm max height

CERAMIC FLATPACK



NOTES:

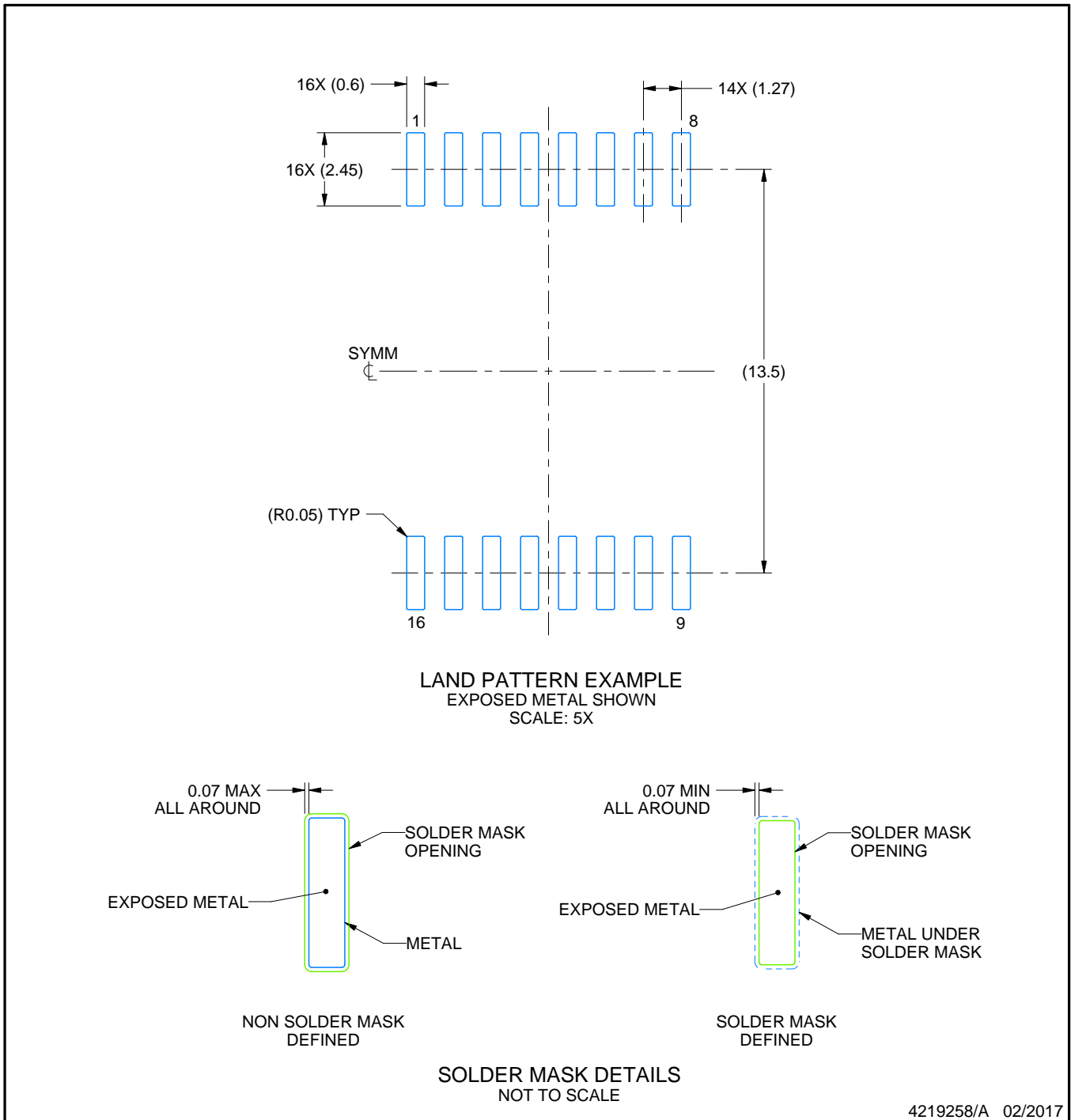
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a metal lid. The lid and heat slug are connected to pin 8.
4. The leads are gold plated.

EXAMPLE BOARD LAYOUT

HKS0016A

CFP - 3.02 mm max height

CERAMIC FLATPACK



NOTES: (continued)

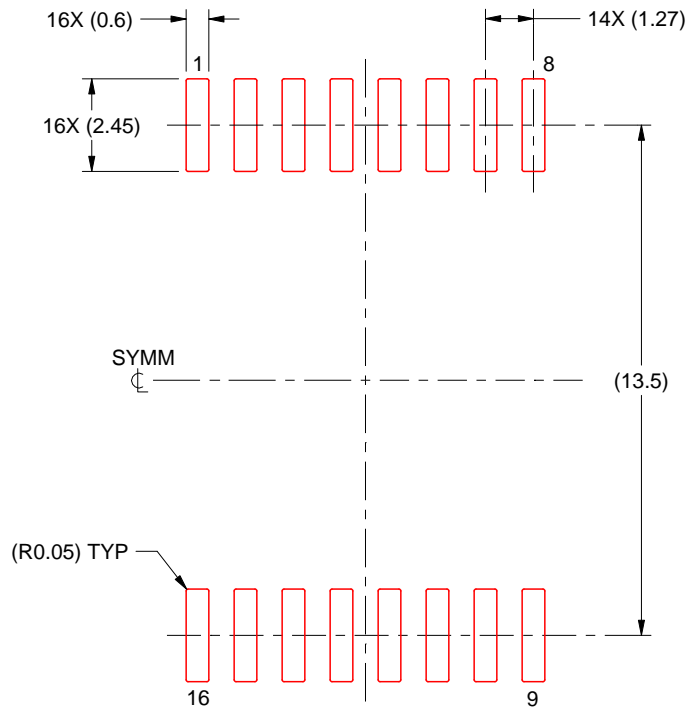
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

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CFP - 3.02 mm max height

CERAMIC FLATPACK



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 5X

4219258/A 02/2017

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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